

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



544249

(43) International Publication Date
30 September 2004 (30.09.2004)

PCT

(10) International Publication Number
WO 2004/083334 A2

(51) International Patent Classification⁷: **C09J 183/07**

PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM,
TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM,
ZW.

(21) International Application Number:
PCT/US2004/008157

(22) International Filing Date: 16 March 2004 (16.03.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/455,193 17 March 2003 (17.03.2003) US

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW),
Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), Euro-
pean (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR,
GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK,
TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW,
ML, MR, NE, SN, TD, TG).

Declarations under Rule 4.17:

- as to applicant's entitlement to apply for and be granted a
patent (Rule 4.17(ii)) for all designations
- as to the applicant's entitlement to claim the priority of the
earlier application (Rule 4.17(iii)) for the following desig-
nations AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW,
BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ,
EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID,
IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU,
LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ,
OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY,
TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA,
ZM, ZW, ARIPO patent (BW, GH, GM, KE, LS, MW, MZ,
SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ,
BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE,
BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE,
IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI patent
(BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE,
SN, TD, TG)
- of inventorship (Rule 4.17(iv)) for US only

Published:

- without international search report and to be republished
upon receipt of that report

For two-letter codes and other abbreviations, refer to the "Guid-
ance Notes on Codes and Abbreviations" appearing at the begin-
ning of each regular issue of the PCT Gazette.

(71) Applicant (for all designated States except US): **DOW
CORNING CORPORATION** [US/US]; 2200 West
Salzburg Road, Midland, MI 48686-0994 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **BHAGWAGAR,**
Dorab, Edul [IN/US]; 2850 Churchill Lane, Saginaw, MI
48603 (US). **DURFEE, Loren** [US/US]; 1807 Burling-
ton Drive, Midland, MI 48642 (US). **LUTZ, Michael**
[US/US]; 408 East Saiko Road, Hope, MI 48628 (US).
MITCHELL, Timothy [US/US]; 508 Clarion Street,
Clio, MI 48420 (US).

(74) Common Representative: **SCADUTO, Patricia, M.;**
Dow Corning Corporation, Intellectual Property Dept.,
Mail CO1232, 2200 West Salzburg Road, Midland, MI
48686-0994 (US).

(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,
MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG,

(54) Title: SOLVENTLESS SILICONE PRESSURE SENSITIVE ADHESIVES WITH IMPROVED HIGH TEMPERATURE CO-
HESIVE STRENGTH

(57) Abstract: This invention relates to silicone compositions suitable for forming pressure sensitive adhesives. More particularly,
the present invention relates to solventless curable PSA compositions suitable for forming pressure sensitive adhesive compositions
having improved high temperature cohesive strength while maintaining good tack and adhesive properties.

WO 2004/083334 A2